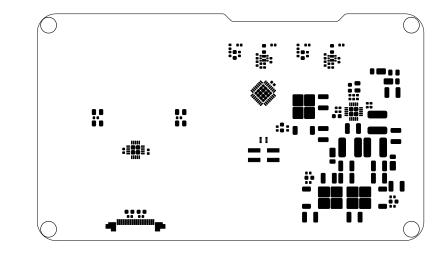
REVISION HISTORY Rev. A INITIAL RELEASE



BOARD CHARACTERISTICS

Copper Layer Count: Board Thickness: 1.6000 mm

Board overall dimensions: 102.3000 mm x 60.0000 mm

Min track/spacing: Copper Finish: ENIG Impedance Control: No Castellated pads: No Plated Board Edge: No

Edge card connectors:

Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Green	3.3	0
F.Cu (Signal)	copper		0.035 mm		1	0
Dielectric	prepreg	FR4	0.1 mm	Not specified	4.5	0.02
In1.Cu (Ground)	copper		0.0152 mm		1	0
Dielectric	core	Copper	0.5548 mm	#D2960FFF	4.5	0.02
In2.Cu (Signal)	copper		0.0152 mm		1	0
Dielectric	prepreg	FR4	0.1 mm	Not specified	4.5	0.02
In3.Cu (Ground)	copper		0.035 mm		1	0
Dielectric	core	FR4	0.5548 mm	Not specified	4.5	0.02
In4.Cu (Power)	copper		0.035 mm		1	0
Dielectric	prepreg	FR4	0.1 mm	Not specified	4.5	0.02
B.Cu (Ground)	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Green	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	White	1	0

NOTES: UNLESS OTHERWISE SPECIFIED

1: MANUFACTURE TO IPC CLASS 2

1590N1 BASEBOARD - PCBA	DRAWN BY	DOCUMEN	T TYPE PCB	DOCUMENT S RELEA	
© Alessandro Rizzoni	APPROVED BY	REVISION A	2023 –	-	SHEET 1/1
		•			_